

ABSTRACT OF THE DISCLOSURE

5 A method of machining a glass substrate by using a  
laser, in which a low-permittivity, low-dielectric-loss  
glass substrate capable of coping with mass production  
processes is made applicable as the substrate of a high-  
frequency circuit intended for microwave and millimeter-  
10 wave bands in particular. For that purpose, a glass  
substrate is provided in which the amount of air bubbles in  
glass is arbitrary controlled to improve the workability of  
the substrate itself. Then, the glass substrate is  
machined while being irradiated with a pulsed laser for a  
15 plurality of times, thereby improving the machining shape  
to the glass substrate. Since glass substrates which are  
typically difficult to machine can be easily applied to the  
fabrication of high-frequency circuits, it becomes possible  
to supply high-performance circuits and apparatuses widely  
20 to the public.